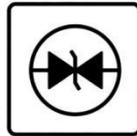


MSKSEMI

SEMICONDUCTOR



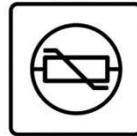
ESD



TVS



TSS



MOV



GDT

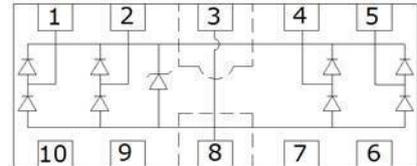


PLED

Product data sheet

Features

- 150 Watts peak pulse power (tp = 8/20µs)
- Transient protection for high speed data lines to IEC 61000-4-2 (ESD) ±15kV (air), ±8kV (contact)
- IEC 61000-4-4 (EFT) 40A (5/50ns)
- Working voltages : 3.3V
- Protects two or four I/O lines
- Ultra Low capacitance:0.3pf (typical between I/O channel)
- Low operating and clamping voltages
- Solid-state silicon avalanche technology



DFN2510P10E

Applications

- High Definition Multi-Media Interface (HDMI)
- USB 1.1/2.0/3.0/OTG
- IEEE 1394 Firewire Ports
- Projection TV Monitors and Flat Panel Displays
- Notebook Computers
- Set Top Box

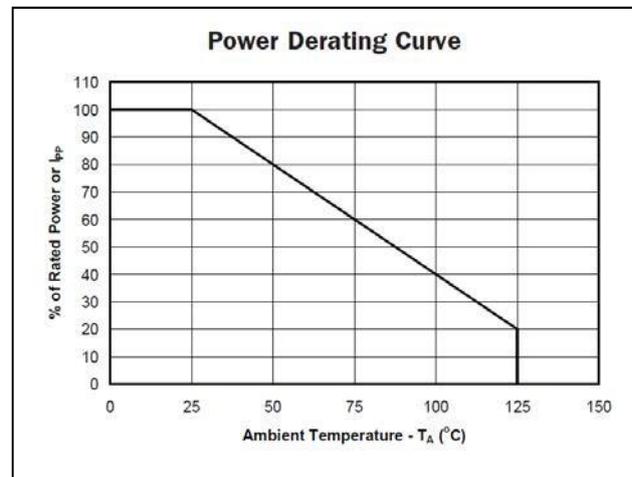
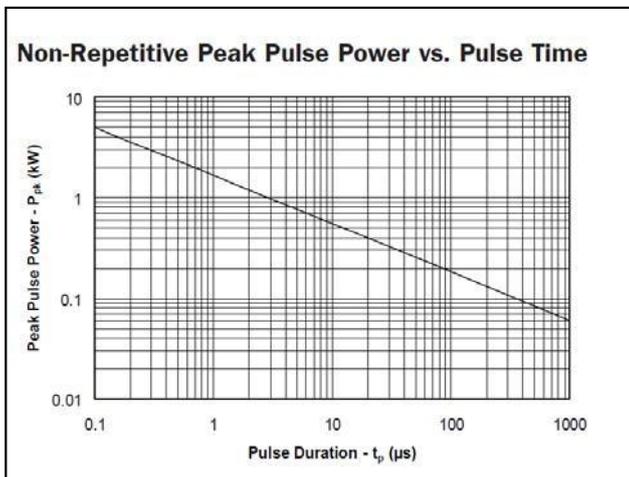
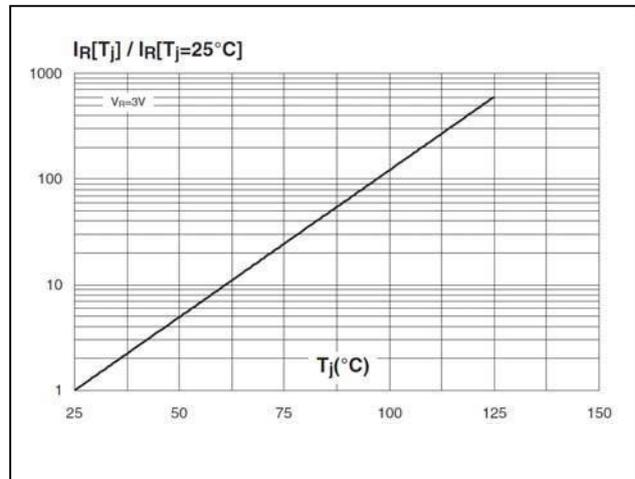
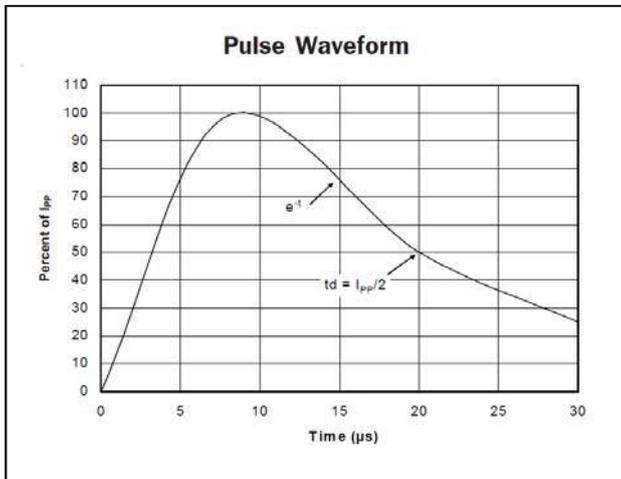
Maximum Rating @ Ta=25°C unless otherwise specified

Symbol	Parameter	Ratings	Units
P _{PK}	Peak Pulse Power (tp = 8/20µs)	150	Watts
T _L	Lead Soldering Temperature	260(10sec.)	°C
T _J	Operating Temperature	-55 to +125	°C
T _{STG}	Storage Temperature	-55 to +150	°C

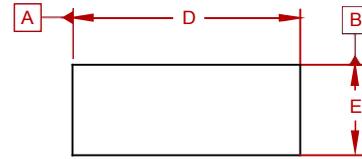
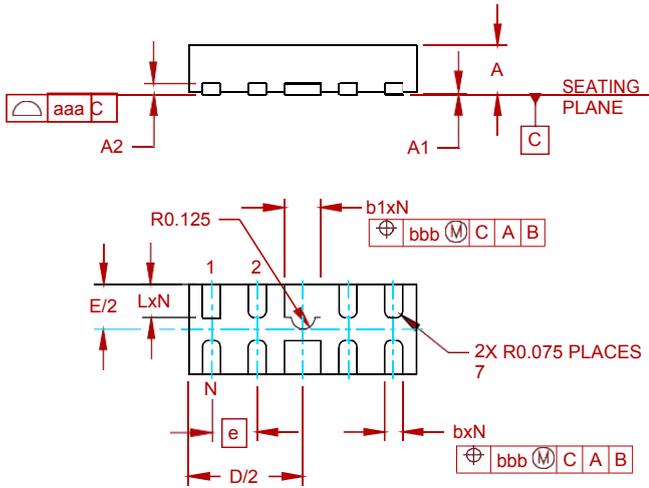
Electrical Characteristics@ Ta=25°C unless otherwise

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
V _{RWM}	Reverse Working Voltage	Any I/O to Ground			3.3	V
V _{BR}	Reverse Breakdown Voltage	I _T = 1mA, Any I/O to Ground	4.5			V
I _R	Reverse Leakage Current	V _{RWM} = 5V, Any I/O to Ground			1	μA
V _F	Diode Forward Voltage	I _F = 15mA		0.85	1.2	V
V _C	Clamping Voltage	I _{PP} = 1A, t _p = 8/20μs, any I/O pin to Ground			9.8	V
		I _{PP} = 5A, t _p = 8/20μs, any I/O pin to Ground			15	V
C _J	Junction Capacitance	V _R = 0V, f = 1MHz, between I/O pins		0.25	0.3	pF
		V _R = 0V, f = 1MHz, any I/O pin to Ground		0.5	0.6	pF

Typical Characteristics@ Ta=25°C unless otherwise specified



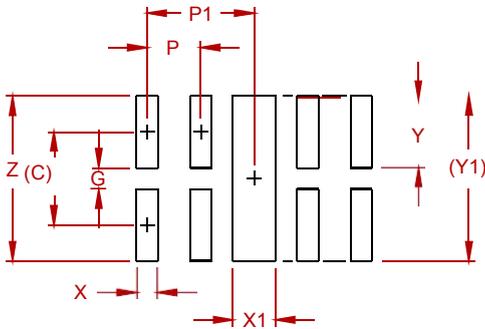
PACKAGE MECHANICAL DATA



DIM	DIMENSI ONS					
	INCHES			MILLIMETERS		
	MIN	NOM	MAX	MIN	NOM	MAX
A	.020	.023	.026	0.50	0.58	0.65
A1	0.00	.001	.002	0.00	0.03	0.05
A2	(.005)			(0.13)		
b	.006	.008	.010	0.15	0.20	0.25
b1	.014	.016	.018	0.35	0.40	0.45
D	.094	.098	.102	2.40	2.50	2.60
E	.035	.039	.043	0.90	1.00	1.10
e	.020 BSC			0.50 BSC		
L	.012	.015	.017	0.30	0.38	0.425
N	8			8		
aaa	.003			0.08		
bbb	.004			0.10		

Dimensions in millimeters

Suggested Pad Layout



DIM	DIMENSIONS	
	INCHES	MILLIMETERS
C	(.034)	(0.875)
G	.008	0.20
P	.020	0.50
P1	.039	1.00
X	.008	0.20
X1	.016	0.40
Y	.027	0.675
Y1	(.061)	(1.55)
Z	.061	1.55

NOTES:

CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
 THIS LAND PATTERN IS FOR REFERENCE PURPOSES ONLY.
 CONSULT YOUR MANUFACTURING GROUP TO ENSURE YOUR COMPANY'S MANUFACTURING GUIDELINES ARE MET.

REEL SPECIFICATION

P/N	PKG	QTY
AZ1143-04F-MS	DFN2510P10E	3000

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